

## 20V P-Channel Power MOSFET

**UM2301S SOT23-3**  
**UM2301P SOT323**

### General Description

The UM2301 is a low threshold P-channel MOSFET, have extremely low on-resistance. This benefit provides the designer with an extremely efficient device for use in battery and load management applications. The device uses a space-saving, small-outline SOT23-3 or SOT323 package.

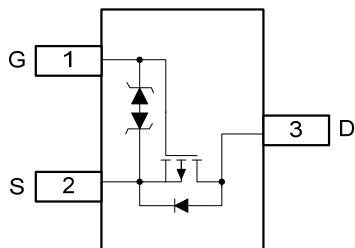
### Applications

- Battery Packs
- Battery-Powered Portable Equipments
- Cellular and Cordless Telephones

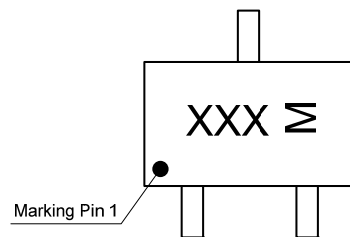
### Features

- Drain-Source Voltage (Max): -20V
- Low On-Resistance:  
200mΩ@V<sub>GS</sub>=-4.5V  
250mΩ@V<sub>GS</sub>=-2.5V
- Continuous Drain Current (Max) :  
-1.5A@25°C (SOT23-3)  
-1.1A@25°C (SOT323)

### Pin Configurations



### Top View



**M: Month Code**  
**XXX: UM2301S 10A**  
**UM2301P VLD**

### Ordering Information

Part Number	Packaging Type	Marking Code	Shipping Qty
UM2301S	SOT23-3	10A	3000pcs/7 Inch Tape & Reel
UM2301P	SOT323	VLD	

**Absolute Maximum Ratings**

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 8$	V
$I_D$	Continuous Drain Current (5s)	SOT23-3	-1.5
		SOT323	-1.1
$I_{DP}$	Drain Current Pulsed (Pulse Width $\leq 10\mu s$ , Duty Cycle $\leq 1\%$ )	-5	A
$P_D$	Power Dissipation	SOT23-3	0.86
		SOT323	0.5
$T_J$	Junction Temperature	-55~150	$^{\circ}C$
$T_{STG}$	Storage Temperature	-55~150	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient ( $\leq 5s$ )	SOT23-3	145
		SOT323	250
ESD	ESD Method 3015.8	2000	V

**Electrical Characteristics ( $T_J=25^{\circ}C$ , unless otherwise noted)**

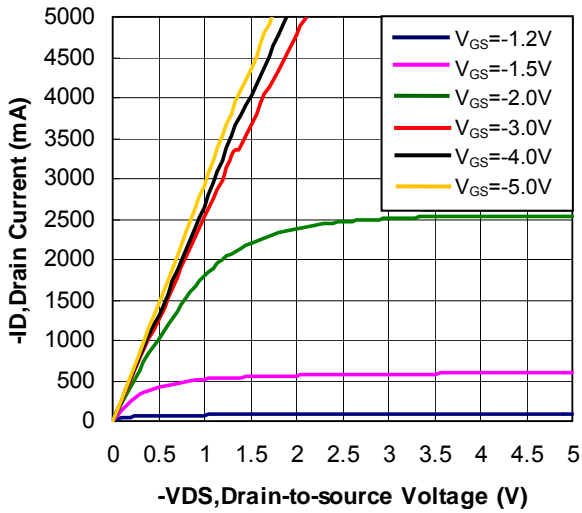
Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-to-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V$			-0.1	$\mu A$
$I_{GSS}$	Gate-to-Source Leakage Current	$V_{GS}=\pm 8V, V_{DS}=0V$			$\pm 10$	$\mu A$
<b>On Characteristics</b>						
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance (Note 1)	$V_{GS}=-4.5V, I_D=-1.0A$		200	350	m $\Omega$
		$V_{GS}=-2.5V, I_D=-1.0A$		250	400	
$V_{GS(TH)}$	Gate-Source Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.6	-1	V
$g_{fs}$	Forward Transconductance (Note 1)	$V_{DS}=-5V, I_D=-2.0A$		4.5		S
<b>Dynamic Characteristics (Note 2)</b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=-10V, f=1.0MHz$		405		pF
$C_{oss}$	Output Capacitance			150		
$C_{rss}$	Reverse Transfer Capacitance			55		
<b>Switching Characteristics (Note 2)</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-10V, R_L=10\Omega, I_D=-1A, V_{GEN}=-4.5V, R_G=1\Omega$		11	20	ns
$t_r$	Rise Time			35	60	
$t_{d(off)}$	Turn-off Delay Time			80	150	
$t_f$	Fall Time			50	90	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$V_{SD}$	Forward Diode Voltage	$I_S=-0.7A$		-0.8	-1.2	V

Note 1: Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

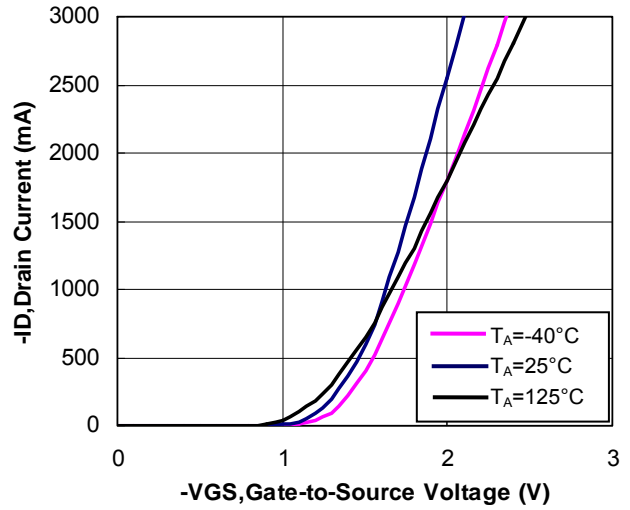
Note 2: Guaranteed by design, not subject to production testing.

## Typical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

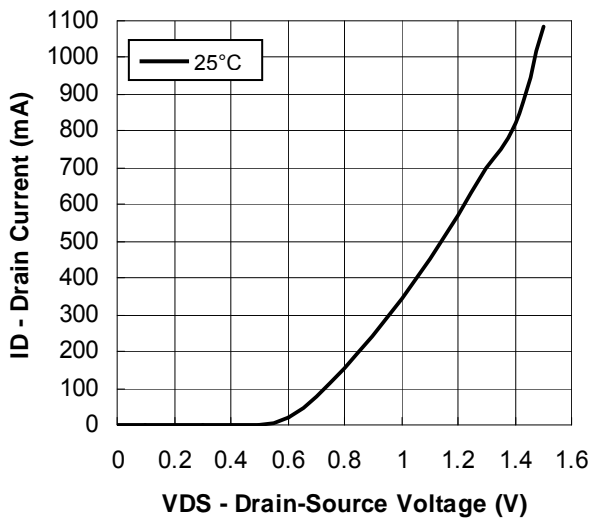
### Output Characteristics



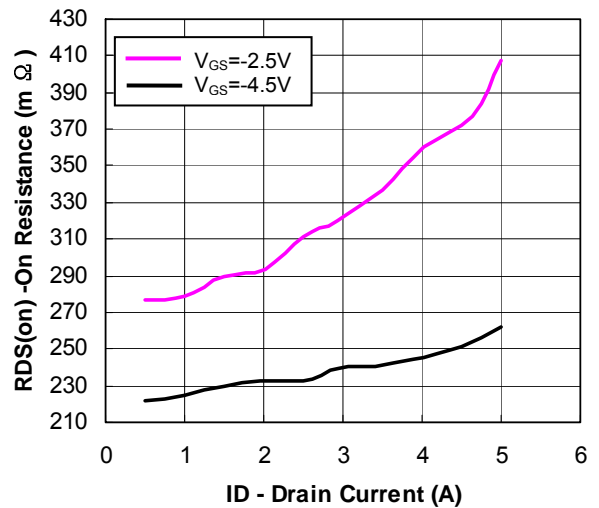
### Transfer Characteristics



### Source-Drain Diode Forward Voltage

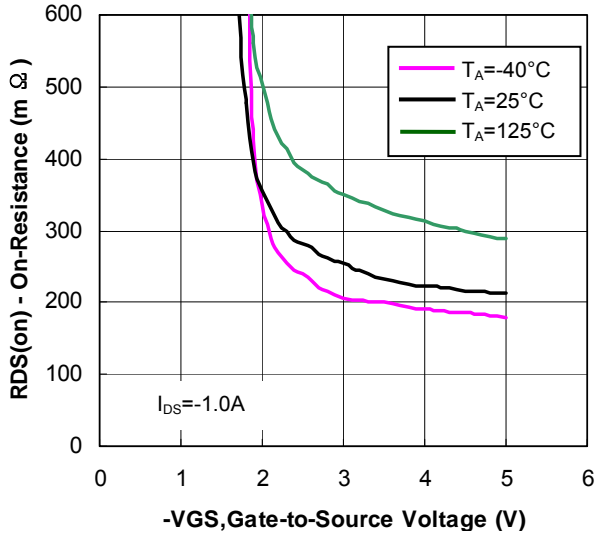


### On Resistance vs. Drain Current

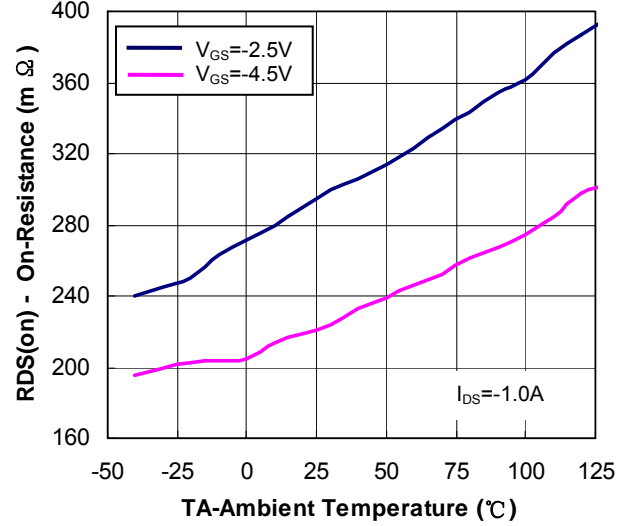


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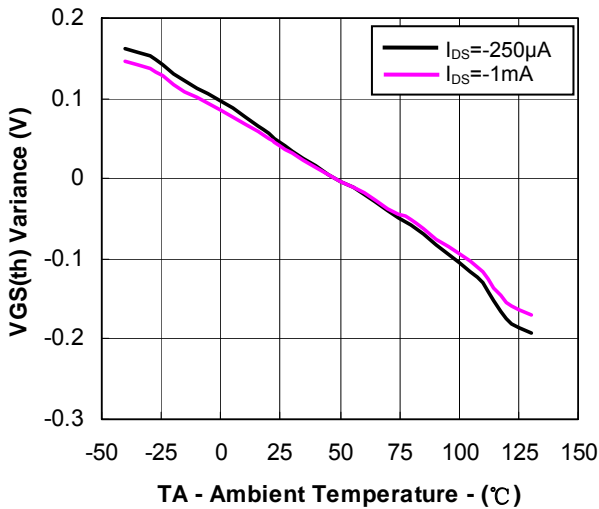
### On-Resistance vs. Gate-to-Source Voltage



### On-Resistance vs. Ambient Temperature



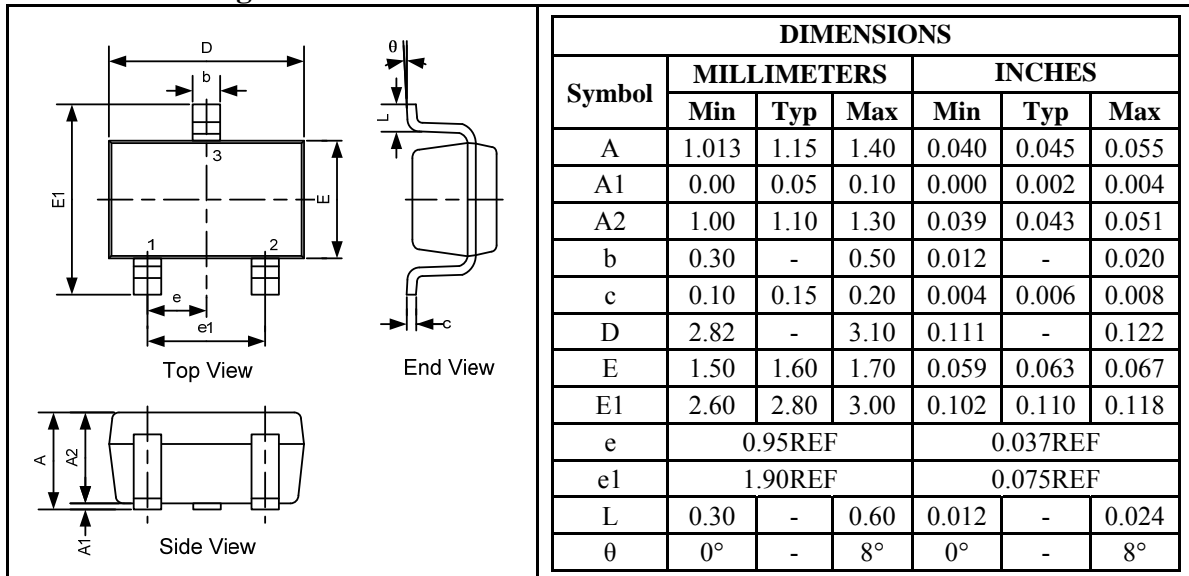
### Threshold Voltage vs. Ambient Temperature



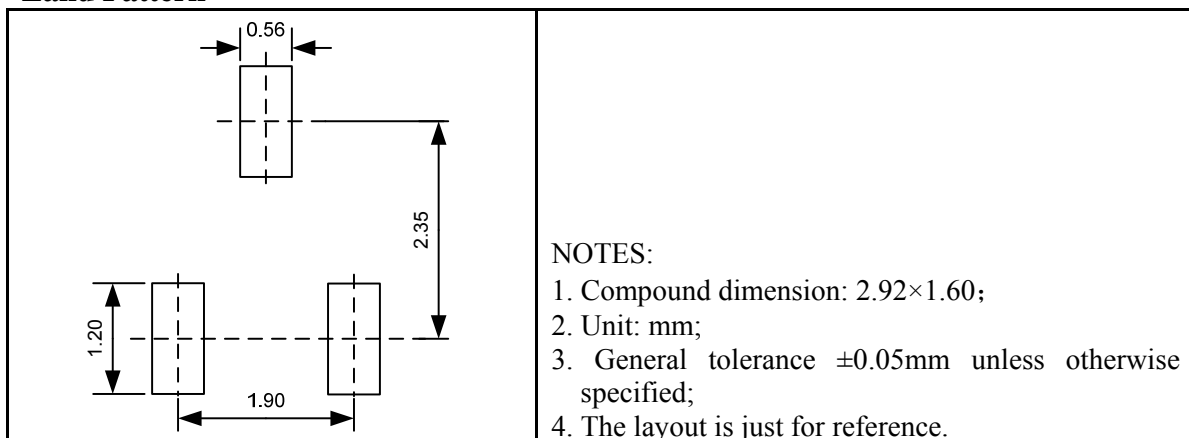
## Package Information

### UM2301S SOT23-3

#### Outline Drawing



#### Land Pattern

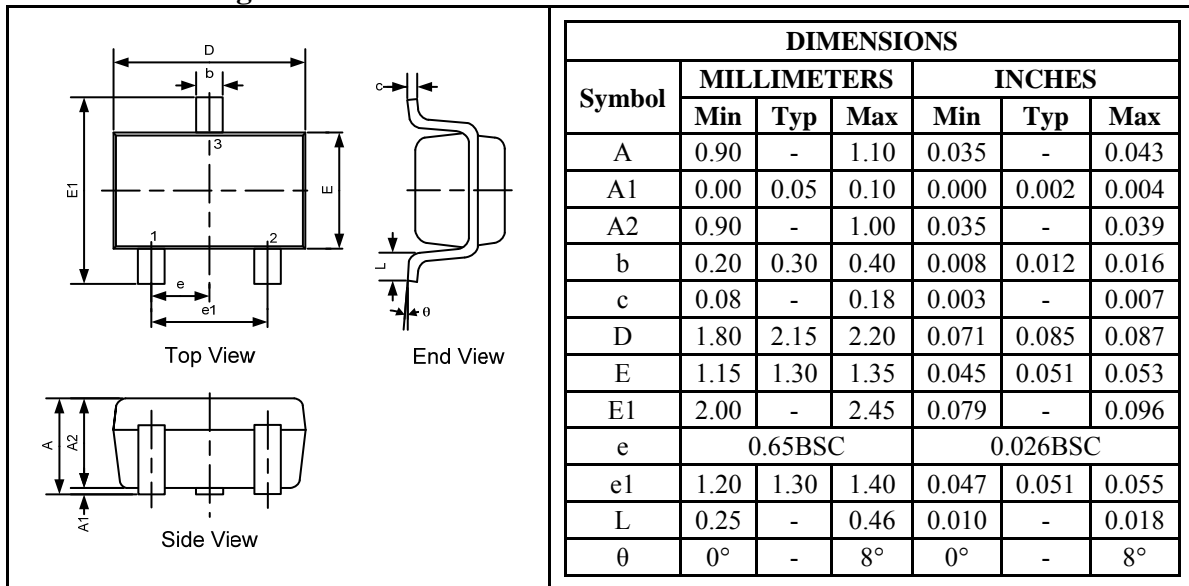


#### Tape and Reel Orientation

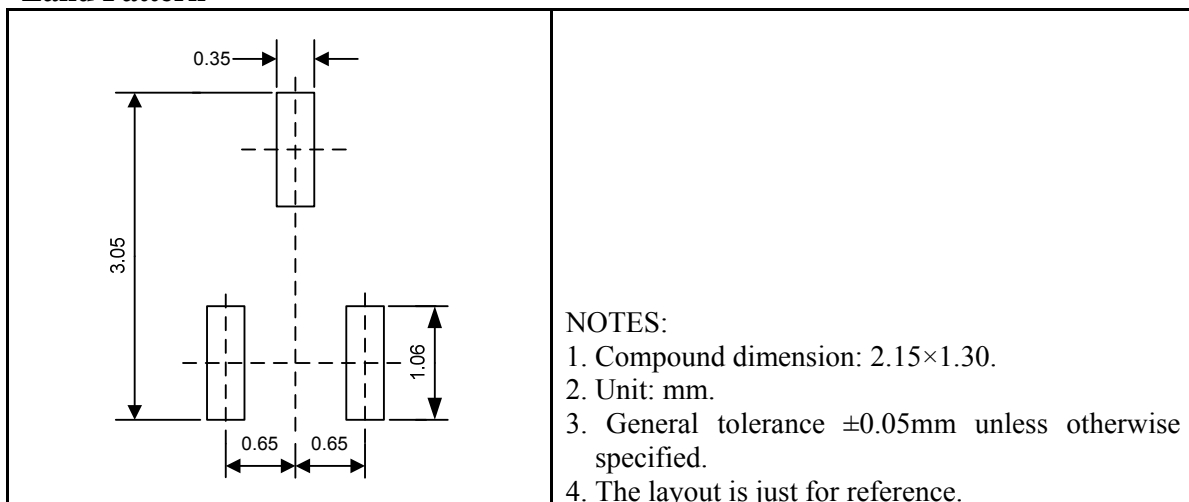


## UM2301P SOT323

### Outline Drawing



### Land Pattern



### Tape and Reel Orientation



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